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CLAIMS

[Utility model registration claim]

[Claim 1] Contact characterized by preparing the metal deposit which made the surface energy fall matter compound in the front face of the part between a soldering terminal area and a contact surface.

[Claim 2] Contact according to claim 1 characterized by the above-mentioned surface energy fall matter being polytetrafluoroethylene.

[Claim 3] Contact according to claim 1 characterized by the above-mentioned surface energy fall matter being fluoride graphite.

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DETAILED DESCRIPTION

[Detailed explanation of a design]

[0001]

[Industrial Application]

Especially this design is related with the contact which can prevent the riser of the flux to a contact surface in the case of soldering of a soldering terminal area in soldering type contact about contact.

[0002]

[Description of the Prior Art]

As preventive measures of the flux riser in contact conventional soldering type, the insulator was formed in the middle part of the soldering terminal area and the other party connector which solder, and the contact surface which performs electrical installation by mold in, and the riser of the flux from a soldering terminal area was prevented.

[0003]

Moreover, by immersing contact into the solution containing surfactants, such as paraxylene hexafluoro RAIDO, as an option, by making the thin film of this chemical form on the front face of contact, surface energy was reduced and the approach referred to as preventing a rise of flux was also taken.

[0004]

[Problem(s) to be Solved by the Device]

by the way -- if it is in the approach of forming an insulator in the part between the soldering terminal area of contact, and a contact surface by the mold in mentioned above -- the configuration of contact -- the mold in technique may be unable to be performed depending on how Moreover, even when the mold in technique was able to be performed, flux went up from the gap of contact and an insulator, as a result it had been said that it resulted even in a contact surface. In this case, the problem that the contact resistance of the contact surface of contact increased arose.

[0005]

Moreover, the approach of applying a surfactant is faced diluting it, and organic solvents, such as chlorofluorocarbon or trichloroethane, must be used for it. However, if an example is taken by ozone layer depletion and global warming destroying earth environment, it is not desirable to use such matter.

[0006]

Furthermore, according to this approach, as mentioned above, an immersion process is needed, and there is a fault referred to as becoming the rise of a manufacturing cost.

[0007]

As for this design, surface energy consists of a polar component and a variance component, the fault of the above-mentioned conventional technique is removed paying attention to the thing with polar low surface energy having high water repellence, and it aims at offering the contact which can prevent the flux riser which can be manufactured cheaply, without destroying earth environment.

[0008]

[Means for Solving the Problem]

According to this design, the contact characterized by preparing the metal deposit which made the

surface energy fall matter compound in the front face of the part between a soldering terminal area and a contact surface is obtained.

[0009]

[Function]

In this design, since the metal deposit which made surface energy fall matter, such as polytetrafluoroethylene (henceforth PTFE) and fluoride graphite, compound is prepared in the front face of the part between the soldering terminal areas and contact surfaces which solder contact, the surface energy of this part falls, it becomes possible to acquire high water repellence, and the flux riser from a soldering terminal area can be effectively prevented in this part.

[0010]

[Example]

Drawing 1 is the perspective view of contact by the 1st example of this design.

[0011]

As shown in drawing 1, the soldering terminal area 2 by which the contact 1 of this example solders to an end, and the contact surface 4 which faces across pars intermedia 3 and performs contact (not shown) and electrical installation of the other party connector to the other end are formed in one with the electrical conducting material.

[0012]

In the case of this example, first, nickel compound plating which contains PTFE as substrate plating is performed to the contact 1 whole by the thickness of 2micro with distributed plating, SnPb plating is performed to the soldering terminal area 2 by the thickness of 2micro, and Au plating has been performed to the contact surface 4 by the thickness of 2micro. Therefore, nickel deposit which compounded PTEF in pars intermedia 3 will be exposed.

[0013]

Drawing 2 is the perspective view of contact by the 2nd example of this design.

[0014]

As shown in drawing 2, the contact 1 and the configuration of the 1st example of the contact 1 of this example are the same, and only deposits differ.

[0015]

In the case of this example, first, nickel plating is performed to the contact 1 whole by the thickness of 2micro as substrate plating, SuPb plating is performed to the soldering terminal area 2 by the thickness of 2micro, and Au plating is performed to a contact surface 4 by the thickness of 2micro. And finally nickel compound plating containing PTFE is deposited by the thickness of 2micro with the partial gilding machine in pars intermedia 3.

[0016]

In addition, although PTFE is used as surface energy fall matter in the 1st and 2nd examples, you may be not only this but fluoride graphite etc. In the case of fluoride graphite, the more the particle is small, it wets wet, a contact angle becomes large, and, the more water repellence is raised.

[0017]

[Effect of the Device]

As mentioned above, even if flux reaches pars intermedia in the case of soldering of a soldering terminal area by preparing the metal deposit which compounded and blamed surface energy fall matter, such as PTFE and fluoride graphite, into the part between the soldering terminal area of contact, and a contact surface in this design, flux is crawled in this part and the contamination of a contact surface and the increase of contact resistance by rise of flux can be prevented effectively.

And in this design, since a surfactant is not used and organic solvents, such as chlorofluocarbon and trichloroethane, are not used, an earth environment top is also desirable, and since the immersion process to the surfactant of contact does not have the need, either, it is possible to manufacture cheaply the contact which can prevent a flux riser.

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DESCRIPTION OF DRAWINGS

[Brief Description of the Drawings]

[Drawing 1] Drawing 1 is the perspective view of contact by the 1st example of this design.

[Drawing 2] Drawing 2 is the perspective view of contact by the 2nd example of this design.

[Description of Notations]

1 Contact

2 Soldering Terminal Area

3 Pars Intermedia

4 Contact Surface

[Translation done.]

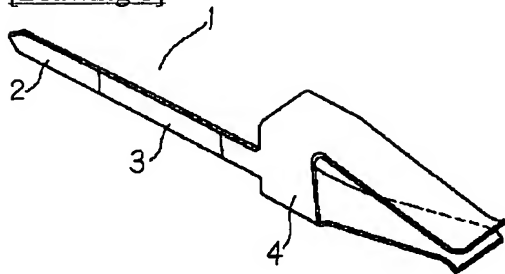
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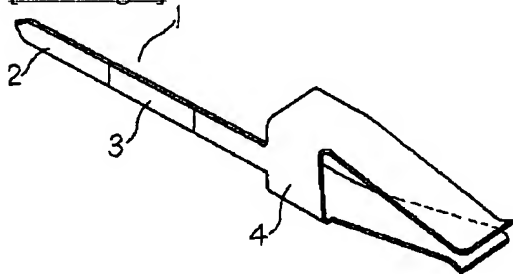
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DRAWINGS

[Drawing 1]



[Drawing 2]



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